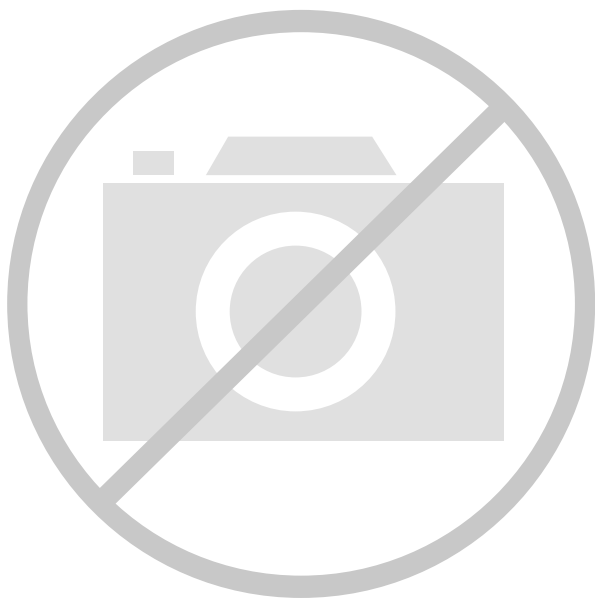




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

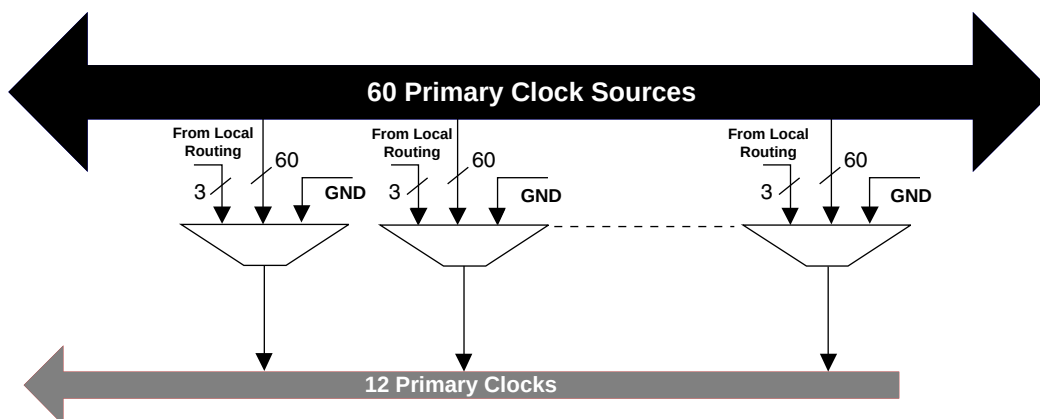
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	476
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFcBGA Rev 2 (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga25ep1-5ffa1020c

Figure 2-6. Per Quadrant Clock Selection

Note: GND is available to switch off the network.

Secondary Clocks

In addition to the primary clock network and edge clocks the LatticeSC devices also contain a secondary clock network. Built of X6 style routing elements this secondary clock network is ideal for routing slower speed clock and control signals throughout the device preserving high-speed clock networks for the most timing critical signals.

Edge Clocks

LatticeSC devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per bank for the top and bottom of the device. The left and right sides have eight edge clocks per side for both banks located on that side. Figure 2-7 shows the arrangement of edge clocks.

Edge clock resources can be driven from a variety of sources. Edge clock resources can be driven from:

- Edge clock PIOs in the same bank
- Primary clock PIOs in the same bank
- Routing
- Adjacent PLLs and DLLs
- ELSR output from the clock divider

Table 2-5. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
FIFO	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output. A clock is required even in asynchronous read mode.

The EBR memory supports two forms of write behavior for dual port operation:

1. **Normal** — data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output.
2. **Write Through** — a copy of the input data appears at the output of the same port.

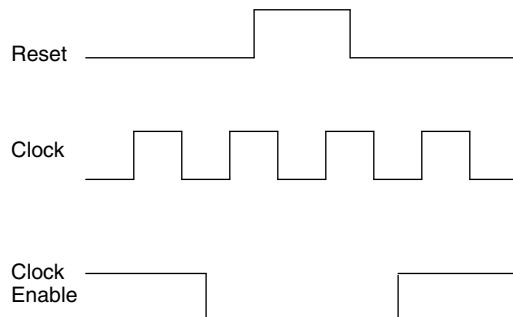
FIFO Configuration

The FIFO has a write port with Data-in, WCE, WE and WCLK signals. There is a separate read port with Data-out, RCE, RE and RCLK signals. The FIFO internally generates Almost Full, Full, Almost Empty, and Empty Flags. The Full and Almost Full flags are registered with WCLK. The Empty and Almost Empty flags are registered with RCLK.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the low-to-high transition of the reset, as shown in Figure 2-16.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM, FIFO and shift register implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-16. The reset timing rules apply to the RPRreset input vs. the RE input and the RST input vs. the WE and RE inputs. Both RST and RPRreset are always asynchronous EBR inputs. For the EBR shift register mode, the GSR signal is always enabled and the local RESET pin is always asynchronous.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled. For more information about on-chip memory, see TN1094, [On-Chip Memory Usage Guide for LatticeSC Devices](#).

Programmable I/O Cells (PIC)

Each PIC contains four PIOs connected to their respective PURESPEED I/O Buffer which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to PURESPEED I/O buffer, and receives input (DI) from the buffer. The PIO contains advanced capabilities to allow the support of speeds up to 2Gbps. These include dedicated shift and DDR logic and adaptive input logic. The dedicated resources simplify the design of robust interfaces.

Table 2-10. Supported Output Standards⁴

Output Standard	Drive	V _{CCIO} (Nom)	On-chip Output Termination
Single-ended Interfaces			
LVTTL/D ¹	8mA, 16mA, 24mA	3.3	None.
LVC MOS33/D ¹	8mA, 16mA, 24mA	3.3	None
LVC MOS25/D ^{1,2}	4mA, 8mA, 12mA, 16mA,	2.5	None, series: 25, 33, 50, 100
LVC MOS18/D ^{1,2}	4mA, 8mA, 12mA, 16mA,	1.8	None, series: 25, 33, 50, 100
LVC MOS15/D ^{1,2}	4mA, 8mA, 12mA, 16mA,	1.5	None, series: 25, 33, 50, 100
LVC MOS12/D ^{1,2}	2mA, 4mA, 8mA, 12mA	1.2	None, series: 25, 33, 50, 100
PCIX15	N/A	1.5	None
PCI33, PCIX33, AGP1X33, AGP2X33	N/A	3.3	None
HSTL18_I	N/A	1.8	None, series: 50
HSTL18_II	N/A	1.8	None, series: 25, series + parallel to V _{CCIO} /2: 25 + 60
HSTL15_I	N/A	1.5	None, series: 50
HSTL15_II	N/A	1.5	None, series: 25, series + parallel to V _{CCIO} /2: 25 + 60
SSTL33_I	N/A	3.3	None
SSTL33_II	N/A	3.3	None
SSTL25_I	N/A	2.5	None, series: 50
SSTL25_II	N/A	2.5	None, series: 33, series + parallel to V _{CCIO} /2: 33+ 60
SSTL18_I	N/A	1.8	None, series: 33
SSTL18_II	N/A	1.8	None, series: 33, series + parallel to V _{CCIO} /2: 33+ 60
Differential Interfaces			
SSTL18D_I	N/A	1.8	None, series: 33
SSTL25D_I	N/A	2.5	None, series: 50
SSTL18D_II, SSTL25D_II	N/A	1.2/2.5/3.3	None, series: 33, series + parallel to V _{CCIO} /2: 33+ 60
SSTL33D_I, II	N/A	3.3	None
HSTL15D_I, HSTL18D_I	N/A	1.5/1.8	None, series: 50
HST15D_II, HSTL18D_II	N/A	1.5/1.8	None, series: 25, series + parallel to V _{CCIO} /2: 25 + 60
LVDS	2mA, 3.5mA, 4mA, 6mA	N/A	None
Mini-LVDS	3.5mA, 4mA, 6mA	N/A	None
BLVDS25	N/A	N/A	None
MLVDS25	N/A	N/A	None
LVPECL33 ³	N/A	3.3	None
RSDS	2mA, 3.5mA, 4mA, 6mA	N/A	None

1. D refers to open drain capability.

2. User can select either drive current or driver impedances but not both.

3. Emulated with external resistors.

4. No GTL or GTL+ support.

PCI Clamp

A programmable PCI clamp is available on the top and bottom banks of the device. The PCI clamp can be turned “ON” or “OFF” on each pin independently. The PCI clamp is used when implementing a 3.3V PCI interface. The

Single Ended Inputs: The SC devices support a number of different termination schemes for single ended inputs:

- Parallel to V_{CCIO} or GND
- Parallel to $V_{CCIO}/2$
- Parallel to V_{TT}

Figure 2-28 shows the single ended input schemes that are supported. The nominal values of the termination resistors are shown in Table 2-9.

Figure 2-28. Input Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Parallel termination to to V_{CCIO} , or parallel to GND receiving end		
Parallel termination to $V_{CCIO}/2$ receiving end		
Parallel termination to V_{TT} at receiving end		

In many situations designers can chose whether to use Thevenin or parallel to V_{TT} termination. The Thevenin approach has the benefit of not requiring a termination voltage to be applied to the device. The parallel to V_{TT} approach consumes less power.

VTT Termination Resources

Each I/O bank, except bank 1, has a number of V_{TT} pins that must be connected if V_{TT} is used. Note V_{TT} pins can sink or source current and the power supply they are connected to must be able to handle the relatively high currents associated with the termination circuits. Note: V_{TT} is not available in all package styles.

On-chip parallel termination to V_{TT} is supported at the receiving end only. On-chip parallel output termination to V_{TT} is not supported.

The V_{TT} internal bus is also connected to the internal V_{CMT} node. Thus in one bank designers can implement either V_{TT} termination or V_{CMT} termination for differential inputs.

DDRII/RLDRAMII Termination Support

The DDR II memory and RLDRAMII (in Bidirection Data mode) standards require that the on-chip termination to V_{TT} be turned on when a pin is an input and off when the pin is an output. The LatticeSC devices contain the required circuitry to support this behavior. For additional detail refer to technical information at the end of the data sheet.

Figure 3-8. Read Mode with Input and Output Registers

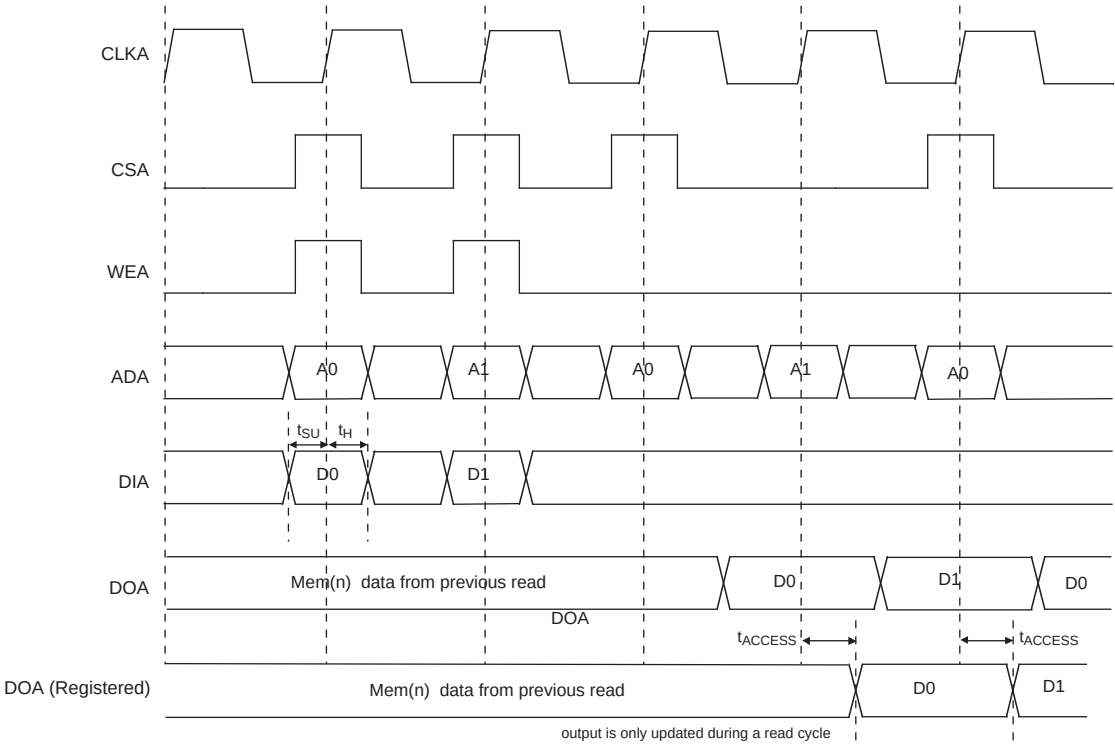
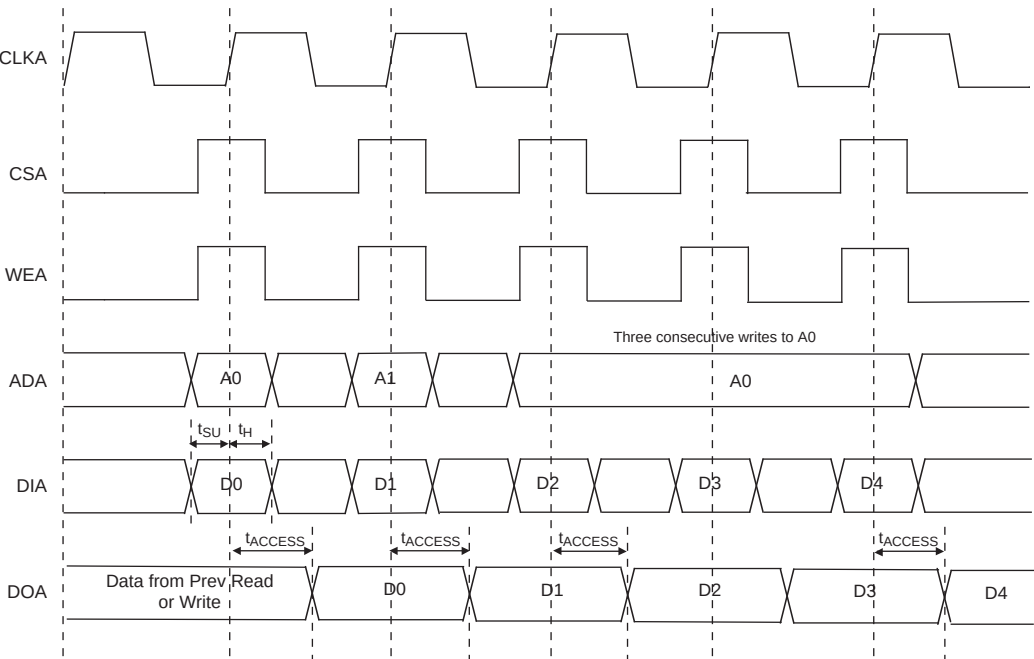


Figure 3-9. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

LFSC/M15 Logic Signal Connections: 256 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
F14	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
E15	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
E14	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
D9	VCCJ	-	
C16	TDO	-	TDO
B15	TMS	-	
B16	TCK	-	
E13	TDI	-	
C14	PROGRAMN	1	
C15	CCLK	1	
A15	PT43D	1	HDC/SI
A14	PT43C	1	LDCN/SCS
B14	PT41A	1	CS1
E12	PT39B	1	CS0N
D13	PT39A	1	RDN
D12	PT37D	1	WRN
E10	PT37C	1	D7
C11	PT37B	1	D6
D10	PT37A	1	D5
A13	PT36D	1	D4
B12	PT36C	1	D3
A12	PT35B	1	D2
C12	PT35A	1	D1
A11	PT33B	1	D0
B11	PT33A	1	QOUT/CEON
E9	PT32D	1	VREF2_1
E8	PT32B	1	DOUT
D8	PT28C	1	BUSYN/RCLK/SCK
A10	PT27B	1	PCLKC1_0
C10	PT27A	1	PCLKT1_0
E7	PT21C	1	VREF1_1
C9	A_VDDIB3_L	-	
A9	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N
A8	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B8	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C8	A_VDDOB3_L	-	
B7	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C7	A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
B6	A_HDINN2_L	-	PCS 360 CH 2 IN N
A6	A_HDINP2_L	-	PCS 360 CH 2 IN P
C6	A_VDDIB2_L	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH11	PB47C	4	PCLKT4_6	PB54C	4	PCLKT4_6
AH10	PB47D	4	PCLKC4_6	PB54D	4	PCLKC4_6
AK12	PB49A	4	PCLKT4_0	PB55A	4	PCLKT4_0
AJ12	PB49B	4	PCLKC4_0	PB55B	4	PCLKC4_0
AF14	PB49C	4	VREF2_4	PB55C	4	VREF2_4
AE14	PB49D	4		PB55D	4	
AL11	PB51A	4	PCLKT4_5	PB57A	4	PCLKT4_5
AL10	PB51B	4	PCLKC4_5	PB57B	4	PCLKC4_5
AH9	PB51C	4		PB57C	4	
AH8	PB51D	4		PB57D	4	
AK11	PB52A	4	PCLKT4_3	PB58A	4	PCLKT4_3
AJ11	PB52B	4	PCLKC4_3	PB58B	4	PCLKC4_3
AH7	PB52C	4	PCLKT4_4	PB58C	4	PCLKT4_4
AH6	PB52D	4	PCLKC4_4	PB58D	4	PCLKC4_4
AK8	PB53A	4		PB67A	4	
AJ8	PB53B	4		PB67B	4	
AF11	PB53C	4		PB67C	4	
AD12	PB55A	4		PB69A	4	
AE12	PB55B	4		PB69B	4	
AM6	PB56A	4		PB70A	4	
AM5	PB56B	4		PB70B	4	
AC12	PB56C	4		PB70C	4	
AL6	PB57A	4		PB73A	4	
AL5	PB57B	4		PB73B	4	
AG7	PB59A	4		PB74A	4	
AG8	PB59B	4		PB74B	4	
AK6	PB60A	4		PB75A	4	
AJ6	PB60B	4		PB75B	4	
AF10	PB60C	4		PB75C	4	
AE11	PB60D	4		PB75D	4	
AM4	PB61A	4		PB77A	4	
AM3	PB61B	4		PB77B	4	
AH5	PB63A	4		PB78A	4	
AH4	PB63B	4		PB78B	4	
AK5	PB64A	4		PB79A	4	
AJ5	PB64B	4		PB79B	4	
AF8	PB64C	4		PB79C	4	
AF7	PB64D	4		PB79D	4	
AL4	PB65A	4		PB81A	4	
AL3	PB65B	4		PB81B	4	
AG5	PB65C	4		PB81C	4	
AF6	PB65D	4		PB81D	4	
AK3	PB67A	4		PB82A	4	
AJ3	PB67B	4		PB82B	4	
AE10	PB67C	4	VREF1_4	PB82C	4	VREF1_4
AD10	PB67D	4		PB82D	4	
AL2	PB68A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB83A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AK2	PB68B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB83B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AE9	PB68C	4		PB83C	4	
AE8	PB68D	4		PB83D	4	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B30	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
D30	A_VDDOB0_L	-		A_VDDOB0_L	-	
A30	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
C31	A_HDINN0_L	-	PCS 360 CH 0 IN N	A_HDINN0_L	-	PCS 360 CH 0 IN N
C32	A_HDINP0_L	-	PCS 360 CH 0 IN P	A_HDINP0_L	-	PCS 360 CH 0 IN P
B31	A_VDDIB0_L	-		A_VDDIB0_L	-	
AL25	NC	-		PB26A	5	
AL24	NC	-		PB26B	5	
AG27	NC	-		PB26C	5	
AH27	NC	-		PB26D	5	
AM25	NC	-		PB27A	5	
AM24	NC	-		PB27B	5	
AL9	NC	-		PB62A	4	
AL8	NC	-		PB62B	4	
AK9	NC	-		PB63A	4	
AJ9	NC	-		PB63B	4	
AG10	NC	-		PB63C	4	
AG11	NC	-		PB63D	4	
J30	NC	-		PL26A	7	
H30	NC	-		PL26B	7	
M28	NC	-		PL26C	7	
N28	NC	-		PL26D	7	
J32	NC	-		PL27A	7	
J31	NC	-		PL27B	7	
N26	NC	-		PL27C	7	
N27	NC	-		PL27D	7	
K31	NC	-		PL29A	7	
K32	NC	-		PL29B	7	
P25	NC	-		PL29C	7	
P26	NC	-		PL29D	7	
L27	NC	-		PL22C	7	
L28	NC	-		PL22D	7	
M29	NC	-		PL30A	7	
L29	NC	-		PL30B	7	
M30	NC	-		PL31A	7	
L30	NC	-		PL31B	7	
L31	NC	-		PL34A	7	
M31	NC	-		PL34B	7	
AA29	NC	-		PL56A	6	
AA30	NC	-		PL56B	6	
AB31	NC	-		PL57A	6	
AA31	NC	-		PL57B	6	
AG30	NC	-		PL57C	6	
AG29	NC	-		PL57D	6	
AB29	NC	-		PL58A	6	
AB30	NC	-		PL58B	6	
Y25	NC	-		PL58C	6	
AA25	NC	-		PL58D	6	
AA8	NC	-		PR58D	3	
Y8	NC	-		PR58C	3	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H21	PT38D	1	D28/PCLKC1_6/MPI_DATA28	PT57D	1	D28/PCLKC1_6/MPI_DATA28
J21	PT38C	1	D29/PCLKT1_6/MPI_DATA29	PT57C	1	D29/PCLKT1_6/MPI_DATA29
A19	PT38B	1	A9/MPI_ADDR23	PT57B	1	A9/MPI_ADDR23
B19	PT38A	1	A10/MPI_ADDR24	PT57A	1	A10/MPI_ADDR24
H22	PT37D	1	D30/PCLKC1_7/MPI_DATA30	PT56D	1	D30/PCLKC1_7/MPI_DATA30
J22	PT37C	1	D31/PCLKT1_7/MPI_DATA31	PT56C	1	D31/PCLKT1_7/MPI_DATA31
F20	PT37B	1	A11/MPI_ADDR25	PT56B	1	A11/MPI_ADDR25
G20	PT37A	1	A12/MPI_ADDR26	PT56A	1	A12/MPI_ADDR26
K21	PT35D	1	D11/MPI_DATA11	PT55D	1	D11/MPI_DATA11
K22	PT35C	1	D12/MPI_DATA12	PT55C	1	D12/MPI_DATA12
A20	PT35B	1	A13/MPI_ADDR27	PT55B	1	A13/MPI_ADDR27
B20	PT35A	1	A14/MPI_ADDR28	PT55A	1	A14/MPI_ADDR28
L21	PT33D	1	A16/MPI_ADDR30	PT53D	1	A16/MPI_ADDR30
L20	PT33C	1	D13/MPI_DATA13	PT53C	1	D13/MPI_DATA13
D20	PT33B	1	A15/MPI_ADDR29	PT53B	1	A15/MPI_ADDR29
E20	PT33A	1	A17/MPI_ADDR31	PT53A	1	A17/MPI_ADDR31
L19	PT30D	1	A19/MPI_TSI21	PT52D	1	A19/MPI_TSI21
K19	PT30C	1	A20/MPI_BDIP	PT52C	1	A20/MPI_BDIP
D21	PT30B	1	A18/MPI_TSI20	PT52B	1	A18/MPI_TSI20
E21	PT30A	1	MPI_TEA	PT52A	1	MPI_TEA
M20	PT28D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
M19	PT28C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F21	PT27B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
G21	PT27A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
H24	B_REFCLKP_L	-		B_REFCLKP_L	-	
J24	B_REFCLKN_L	-		B_REFCLKN_L	-	
L22	VCC12	-		VCC12	-	
E26	B_VDDIB3_L	-		B_VDDIB3_L	-	
G22	VCC12	-		VCC12	-	
E22	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
F22	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
L24	VCC12	-		VCC12	-	
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D22	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D23	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
K24	VCC12	-		VCC12	-	
F23	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
E23	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
D26	B_VDDIB2_L	-		B_VDDIB2_L	-	
G23	VCC12	-		VCC12	-	
D27	B_VDDIB1_L	-		B_VDDIB1_L	-	
G24	VCC12	-		VCC12	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).

2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN33	PB3B	5	LLC_PLLC_IN_A/LLC_PLLC_FB_B
AH29	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AJ29	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AM32	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AM31	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AG27	PB4C	5	
AG26	PB4D	5	
AL29	PB5A	5	
AL28	PB5B	5	
AH27	PB5C	5	
AH26	PB5D	5	VREF1_5
AN32	PB7A	5	
AP32	PB7B	5	
AF25	PB7C	5	
AE25	PB7D	5	
AN31	PB11A	5	
AN30	PB11B	5	
AK29	PB11C	5	
AK28	PB11D	5	
AP31	PB12A	5	
AP30	PB12B	5	
AD24	PB12C	5	
AE24	PB12D	5	
AM29	PB15A	5	
AM28	PB15B	5	
AJ27	PB15C	5	
AJ26	PB15D	5	
AP29	PB16A	5	
AP28	PB16B	5	
AK27	PB16C	5	
AK26	PB16D	5	
AN29	PB19A	5	
AN28	PB19B	5	
AG25	PB19C	5	
AG24	PB19D	5	
AL26	PB20A	5	
AL25	PB20B	5	
AG23	PB20C	5	
AG22	PB20D	5	
AN27	PB23A	5	
AN26	PB23B	5	
AF24	PB23C	5	
AF23	PB23D	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AP27	PB26A	5	
AP26	PB26B	5	
AK25	PB26C	5	
AK24	PB26D	5	
AN25	PB29A	5	
AN24	PB29B	5	
AE22	PB29C	5	
AE21	PB29D	5	
AM26	PB31A	5	
AM25	PB31B	5	
AF22	PB31C	5	
AF21	PB31D	5	
AN23	PB47A	5	
AN22	PB47B	5	
AP23	PB57A	5	
AP22	PB57B	5	
AG21	PB57C	5	
AG20	PB57D	5	
AP25	PB50A	5	PCLKT5_3
AP24	PB50B	5	PCLKC5_3
AD21	PB50C	5	PCLKT5_4
AD20	PB50D	5	PCLKC5_4
AL23	PB51A	5	PCLKT5_5
AL22	PB51B	5	PCLKC5_5
AH24	PB51C	5	
AH23	PB51D	5	
AM23	PB53A	5	PCLKT5_0
AM22	PB53B	5	PCLKC5_0
AJ24	PB53C	5	
AJ23	PB53D	5	VREF2_5
AN21	PB54A	5	PCLKT5_1
AN20	PB54B	5	PCLKC5_1
AE19	PB54C	5	PCLKT5_6
AD19	PB54D	5	PCLKC5_6
AK21	PB55A	5	PCLKT5_2
AK20	PB55B	5	PCLKC5_2
AK23	PB55C	5	PCLKT5_7
AK22	PB55D	5	PCLKC5_7
AL20	PB58A	5	
AL19	PB58B	5	
AG19	PB58C	5	
AF19	PB58D	5	
AP21	PB61A	5	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F25	B_HDINN0_L	-	PCS 361 CH 0 IN N
E25	B_HDINP0_L	-	PCS 361 CH 0 IN P
D28	B_VDDIB0_L	-	
G25	VCC12	-	
D29	A_VDDIB3_L	-	
C25	VCC12	-	
A25	A_HDINP3_L	-	PCS 360 CH 3 IN P
B25	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
E27	VCC12	-	
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
F26	A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
F27	A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
E28	VCC12	-	
B28	A_HDINN2_L	-	PCS 360 CH 2 IN N
A28	A_HDINP2_L	-	PCS 360 CH 2 IN P
D30	A_VDDIB2_L	-	
C28	VCC12	-	
D31	A_VDDIB1_L	-	
C29	VCC12	-	
A29	A_HDINP1_L	-	PCS 360 CH 1 IN P
B29	A_HDINN1_L	-	PCS 360 CH 1 IN N
A30	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
E29	VCC12	-	
B30	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
F28	A_VDDOB1_L	-	
B31	A_HDOUTN0_L	-	PCS 360 CH 0 OUT N
F29	A_VDDOB0_L	-	
A31	A_HDOUTP0_L	-	PCS 360 CH 0 OUT P
E30	VCC12	-	
B32	A_HDINN0_L	-	PCS 360 CH 0 IN N
A32	A_HDINP0_L	-	PCS 360 CH 0 IN P
D32	A_VDDIB0_L	-	
C32	VCC12	-	
E34	PL30A	7	
F34	PL30B	7	
F33	PL34A	7	
G33	PL34B	7	
K30	PL38A	7	
L30	PL38B	7	
G34	PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2}

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G34	A_REFCLKP_L	-		A_REFCLKP_L	-	
H34	A_REFCLKN_L	-		A_REFCLKN_L	-	
N30	VCC12	-		VCC12	-	
H33	RESP_ULC	-		RESP_ULC	-	
P25	RESETN	1		RESETN	1	
P26	TSALLN	1		TSALLN	1	
P31	DONE	1		DONE	1	
P23	INITN	1		INITN	1	
P30	M0	1		M0	1	
P22	M1	1		M1	1	
P24	M2	1		M2	1	
R22	M3	1		M3	1	
J37	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
J38	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
P32	PL16C	7		PL15C	7	
R32	PL16D	7		PL15D	7	
G40	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
H40	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N33	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P33	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
G41	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
H41	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
T29	PL18C	7		PL18C	7	
U29	PL18D	7	VREF2_7	PL18D	7	VREF2_7
G42	PL20A	7		PL19A	7	
H42	PL20B	7		PL19B	7	
M34	PL20C	7		PL19C	7	
M35	PL20D	7		PL19D	7	
K37	PL21A	7		PL26A	7	
L37	PL21B	7		PL26B	7	
N34	PL21C	7		PL26C	7	
P34	PL21D	7		PL26D	7	
K38	PL22A	7		PL30A	7	
L38	PL22B	7		PL30B	7	
T33	PL22C	7		PL30C	7	
R33	PL22D	7		PL30D	7	
J41	PL24A	7		PL34A	7	
K41	PL24B	7		PL34B	7	
U31	PL24C	7		PL34C	7	
V31	PL24D	7		PL34D	7	
K42	PL25A	7		PL38A	7	
J42	PL25B	7		PL38B	7	
J36	PL25C	7		PL38C	7	
K36	PL25D	7		PL38D	7	
N38	PL26A	7		PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AP26	PB41C	5		PB43C	5	
AN26	PB41D	5		PB43D	5	
AY30	PB43A	5		PB45A	5	
AY29	PB43B	5		PB45B	5	
AU30	PB43C	5		PB45C	5	
AU31	PB43D	5		PB45D	5	
AV27	PB44A	5		PB46A	5	
AV26	PB44B	5		PB46B	5	
AT28	PB44C	5		PB46C	5	
AT27	PB44D	5		PB46D	5	
BA29	PB45A	5		PB47A	5	
BA28	PB45B	5		PB47B	5	
AL25	PB45C	5		PB47C	5	
AM25	PB45D	5		PB47D	5	
BB29	PB47A	5		PB49A	5	
BB28	PB47B	5		PB49B	5	
AN25	PB47C	5		PB49C	5	
AP25	PB47D	5		PB49D	5	
AY27	PB48A	5	PCLKT5_3	PB50A	5	PCLKT5_3
AY26	PB48B	5	PCLKC5_3	PB50B	5	PCLKC5_3
AT25	PB48C	5	PCLKT5_4	PB50C	5	PCLKT5_4
AT24	PB48D	5	PCLKC5_4	PB50D	5	PCLKC5_4
AW27	PB49A	5	PCLKT5_5	PB51A	5	PCLKT5_5
AW26	PB49B	5	PCLKC5_5	PB51B	5	PCLKC5_5
AU29	PB49C	5		PB51C	5	
AU28	PB49D	5		PB51D	5	
BB27	PB51A	5	PCLKT5_0	PB53A	5	PCLKT5_0
BB26	PB51B	5	PCLKC5_0	PB53B	5	PCLKC5_0
AR25	PB51C	5		PB53C	5	
AR24	PB51D	5	VREF2_5	PB53D	5	VREF2_5
BA27	PB52A	5	PCLKT5_1	PB54A	5	PCLKT5_1
BA26	PB52B	5	PCLKC5_1	PB54B	5	PCLKC5_1
AP24	PB52C	5	PCLKT5_6	PB54C	5	PCLKT5_6
AN24	PB52D	5	PCLKC5_6	PB54D	5	PCLKC5_6
AV25	PB53A	5	PCLKT5_2	PB55A	5	PCLKT5_2
AV24	PB53B	5	PCLKC5_2	PB55B	5	PCLKC5_2
AU27	PB53C	5	PCLKT5_7	PB55C	5	PCLKT5_7
AU26	PB53D	5	PCLKC5_7	PB55D	5	PCLKC5_7
BA25	PB55A	5		PB57A	5	
BA24	PB55B	5		PB57B	5	
AU24	PB55C	5		PB57C	5	
AU25	PB55D	5		PB57D	5	
BB24	PB56A	5		PB58A	5	
BB25	PB56B	5		PB58B	5	
AM23	PB56C	5		PB58C	5	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
K14	VCC12	-		VCC12	-	
H11	B_VDDIB2_R	-		B_VDDIB2_R	-	
D8	B_HDINP2_R	-	PCS 3E1 CH 2 IN P	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
E8	B_HDINN2_R	-	PCS 3E1 CH 2 IN N	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
G5	VCC12	-		VCC12	-	
B9	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
L12	B_VDDOB2_R	-		B_VDDOB2_R	-	
A9	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
C5	B_VDDOB3_R	-		B_VDDOB3_R	-	
A10	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
H5	VCC12	-		VCC12	-	
B10	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
E9	B_HDINN3_R	-	PCS 3E1 CH 3 IN N	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
D9	B_HDINP3_R	-	PCS 3E1 CH 3 IN P	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
J13	VCC12	-		VCC12	-	
H12	B_VDDIB3_R	-		B_VDDIB3_R	-	
J12	VCC12	-		VCC12	-	
M14	B_REFCLKN_R	-		B_REFCLKN_R	-	
L14	B_REFCLKP_R	-		B_REFCLKP_R	-	
J14	VCC12	-		VCC12	-	
G12	C_VDDIB0_R	-		C_VDDIB0_R	-	
D10	C_HDINP0_R	-	PCS 3E2 CH 0 IN P	C_HDINP0_R	-	PCS 3E2 CH 0 IN P
E10	C_HDINN0_R	-	PCS 3E2 CH 0 IN N	C_HDINN0_R	-	PCS 3E2 CH 0 IN N
H6	VCC12	-		VCC12	-	
B11	C_HDOUTP0_R	-	PCS 3E2 CH 0 OUT P	C_HDOUTP0_R	-	PCS 3E2 CH 0 OUT P
M12	C_VDDOB0_R	-		C_VDDOB0_R	-	
A11	C_HDOUTN0_R	-	PCS 3E2 CH 0 OUT N	C_HDOUTN0_R	-	PCS 3E2 CH 0 OUT N
L11	C_VDDOB1_R	-		C_VDDOB1_R	-	
A12	C_HDOUTN1_R	-	PCS 3E2 CH 1 OUT N	C_HDOUTN1_R	-	PCS 3E2 CH 1 OUT N
K11	VCC12	-		VCC12	-	
B12	C_HDOUTP1_R	-	PCS 3E2 CH 1 OUT P	C_HDOUTP1_R	-	PCS 3E2 CH 1 OUT P
E11	C_HDINN1_R	-	PCS 3E2 CH 1 IN N	C_HDINN1_R	-	PCS 3E2 CH 1 IN N
D11	C_HDINP1_R	-	PCS 3E2 CH 1 IN P	C_HDINP1_R	-	PCS 3E2 CH 1 IN P
H13	VCC12	-		VCC12	-	
C6	C_VDDIB1_R	-		C_VDDIB1_R	-	
H15	VCC12	-		VCC12	-	
G13	C_VDDIB2_R	-		C_VDDIB2_R	-	
D12	C_HDINP2_R	-	PCS 3E2 CH 2 IN P	C_HDINP2_R	-	PCS 3E2 CH 2 IN P
E12	C_HDINN2_R	-	PCS 3E2 CH 2 IN N	C_HDINN2_R	-	PCS 3E2 CH 2 IN N
J9	VCC12	-		VCC12	-	
B13	C_HDOUTP2_R	-	PCS 3E2 CH 2 OUT P	C_HDOUTP2_R	-	PCS 3E2 CH 2 OUT P
K10	C_VDDOB2_R	-		C_VDDOB2_R	-	
A13	C_HDOUTN2_R	-	PCS 3E2 CH 2 OUT N	C_HDOUTN2_R	-	PCS 3E2 CH 2 OUT N
J10	C_VDDOB3_R	-		C_VDDOB3_R	-	
A14	C_HDOUTN3_R	-	PCS 3E2 CH 3 OUT N	C_HDOUTN3_R	-	PCS 3E2 CH 3 OUT N

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSC3GA115E-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Date	Version	Section	Change Summary
June 2006 (cont.)	01.2 (cont.)	DC and Switching Characteristics (cont.)	Updated Typical Building Block Performance with ispLEVER 6.0 values.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 values.
			Updated Lattice SC Internal Timing Parameters with ispLEVER 6.0 values.
			Updated Lattice SC Family Timing Adders with ispLEVER 6.0 values
			Changed % spread from 1 to 0.5 min and from 3 to 1.5 max.
			Changed conditions to refer to “with multiplication” and “without multiplication”.
			Changed the formula for t_{OPJIT} with multiplication (same result, different representation).
		Pinout Information	Expanded definition of NC.
			Expanded definition of GND.
			Expanded definition of VTT_x.
			Expanded definition of VCC12.
			Added accuracy of TEMP pin.
			Added RESPN_[ULC/URC].
			Updated Pin Information Summary with additional devices and packages.
			Added additional devices and packages pinouts.
			Removed Power Supply and NC connections table
			Removed VTT table
			Removed LFSC25 Logic Signal Connections: 900-Ball fBGA1 table
			Changed all VDDP, VDDTX and VDDR _X to VCC12.
		Ordering Information	Added dual marking.
			Added lead free packaging information to part number description.
August 2006	01.3	Introduction	Added SC40 1152 information to Table 1-1.
			Updated Table 1-3 with ispLEVER 6.0 SP1 results.
		Architecture	Added SSTL18 II to Table 2-8.
			Changed Table 2-10 VCCIO column to “N/A” for LVDS, mini-LVDS, BLVDS25, MLVDS25, HYPT and RSDS.
			Changed Hypertransport performance to 700 MHz (1400 Mbps) in Table 2-11.
			Changed SPI4.2 performance to 500 MHz (1000 Mbps) in Table 2-11
			Added “On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.”
			Added VCCIO of 2.5 V for LVPECL33 in table 2-9.
		DC and Switching Characteristics	Updated Typical Building Block Performance with ispLEVER 6.0 SP1 results.
			Updated Initialization and Standby Supply Current table to break out ICC and ICC12.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 SP1 results.
			Updated LatticeSC Internal Timing Parameters with ispLEVER 6.0 SP1 results.

Date	Version	Section	Change Summary
December 2011	02.4	DC and Switching Characteristics	Updated JTAG Port Timing Specifications table.